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MATERIALS SUBSTRATES

- Silicon Wafers J 04
- Single Crystal Substrates..... J 07
- Glass & Fused Quartz Substrates..... J 44
- Ceramic Substrates J 48
- Glassy Carbon Substrates J 49
- HOPG & Mica Substrates J 51
- Thin Film Deposition J 54
- Wafer Tweezers..... J 56

NEYCO has a complete range of crystal substrates for a wide variety of applications, including Semiconductor, Biotechnology, Nanotechnology, and MEMS. NEYCO is your one stop source for advanced materials for both R&D laboratory use and industry production. We can help you to locate, specify, and purchase unique materials in an efficient and cost effective manner.



STANDARD SUBSTRATE PARAMETERS

Substrates and wafers are manufactured by a technology, which is specially adapted to the respective material. Additionally we produce substrates and wafers customer-specific in all possible orientations, sizes and geometries and with smaller tolerance.

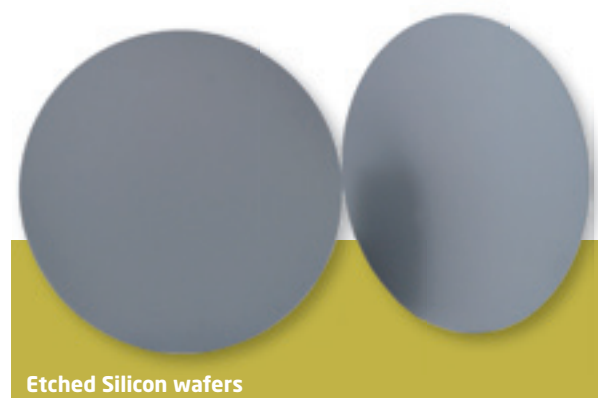
Orientations	(100), (111), (110) for cubic crystals (110), (001) for tetragonal crystals (0001), (1-102), (11-20), (10-10) for hexagonal crystals (110), (001) for orthorhombic crystals other orientations on request Standard: edges are oriented
Tolerance of orientation	Maximum 30' ; typical < 20' higher precision on request
Standard sizes	10x10 mm, 10x5 mm, 12.7x12.7 mm, 15x15 mm, 20x20 mm, 25x25 mm, ø 1", ø 2", ø 3" other sizes on request
Tolerance of sizes	+0/-0.05 mm
Thickness	0.5 mm, 1.0 mm (standard) other thicknesses down to 0.1 mm on request
Tolerance of thickness	+0.05/-0.05 mm
Polish	One side, two sides optical polish of lateral sides (cylinders) on request
Surface quality	Scratchfree at magnification of 50
Roughness: (at $\lambda_{\text{cutoff}} = 0.08 \text{ mm}$)	Ra: typ. better than 0.5 nm Rq: typ. better than 1.0 nm Rt: typ. better than 2.0 nm
Parallelity	Typ. better than 10'
Flatness	Max. 1 $\mu\text{m}/10 \text{ mm}$ (test region 98% of the wafer area)

Micro-roughness measured with Kugler Interferometermicroscope (lateral resolution: 0.64 μm , vertical resolution (theoretically): 0.01 nm).

Silicon Wafers

MATERIALS CHARACTERISTICS

Silicon wafers are cut from silicon single crystal using internal diameter diamond discs. Silicon wafers are lapped of both sides with abrasive mixture. After cutting or lapping the wafers are washed in ultrasonic washers or undergo active washing. The wafers' edges are mechanically rounded. Silicon wafers are etched in acid mixture or alkaline. Wafers surface is alkaline or acid etched according to the customer's request. Active sides of the wafers (for single side polished wafers) or both sides (for two sides polished wafers) are chemo-mechanically polished.

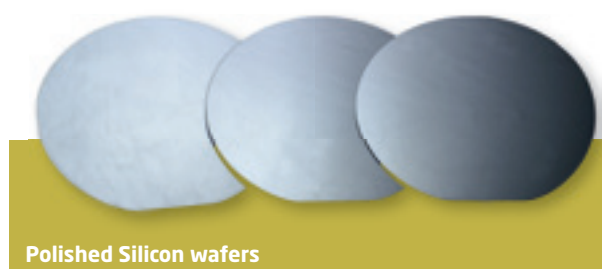


Etched Silicon wafers

APPLICATIONS

Wafers are used for production of silicon substrates and membranes.

The below mentioned parameters are dealing with our standard production. On the customer's request we are ready to discuss orders for wafers with some other parameters, for instance:



Polished Silicon wafers

- Low radial resistivity variation (RRV) combined with the uniform distribution of dopants in the crystal (this parameter depends on shape of phase boundary and the phenomena in the boundary layer during monocrystallization process).
- Perfect crystallographic structure of material (free from swirls, with dislocations density lower than recommended by SEMI standard - $500/\text{cm}^2$).
- Low oxygen concentration ($\text{O}_2 < 30 \text{ ppm}$).
- Tolerance of orientation better than 0.10° .
- Very good polished surface (one or both sides polished depending on technology and the type of products).

STANDARD SPECIFICATIONS

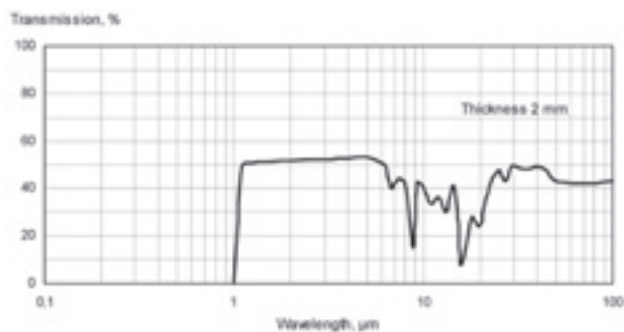
CRYSTAL GROWTH						
Growth method	Czochralski (CZ) Floating zone (FZ)					
Orientation	<111>, <100>					
Diameters	1" to 300 mm					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Cubic a = 0.543 nm					
Dopant available	P-type: Boron N-type: Phosphorus, Antimony or Arsenic					
PHYSICAL PROPERTIES						
Density	2.329 g.cm ⁻³					
Melting point	1417°C					
Hardness	7 Mohs					
Thermal expansion	2.3.10 ⁻⁶ K ⁻¹					
Resistivity range	0.001 - 10 000 Ω.cm					
Band gap (at 273 K)	1.106 eV					
Thermal conductivity	147 W.m ⁻¹ .K ⁻¹					
Carrier mobility	μ _e = 1350 cm ² .V ⁻¹ .s ⁻¹ μ _h = 480 cm ² .V ⁻¹ .s ⁻¹					
Conductivity type	P-type or N-type					
CHEMICAL PROPERTIES						
Solubility in water	0.005 g/100 cm ³					
Solubility in acids	Soluble					
Solubility in organic solvents	Insoluble					
OPTICAL PROPERTIES						
Absorption coefficient	0.01 cm ⁻¹ at 5 μm					
Transmission range (thickness 2 mm)	1.2 - 15.0 μm					
Refractive index n	3.0 μm	5.0 μm	6.0 μm	7.0 μm	8.0 μm	10.0 μm
	3.432	3.422	3.420	3.419	3.418	3.417

TECHNICAL DATA : AS CUT, LAPPED, ETCHED, POLISHED

Diameter (mm)	50.8 ± 0.3	76.0 ± 0.5	100 ± 0.5	125 ± 0.5	150 ± 0.5
Orientation	<100>	<100>	<100>	<100>	<100>
Thickness (μm)	40 to 25000	60 to 25000	70 to 25000	100 to 5000	150 to 5000
Thickness tolerance (μm)					
Standard	± 25	± 25	± 25	± 25	± 25
Typical	± 10	± 10	± 15	± 20	± 20
Total thickness variation TTV max	10	15	15	20	25

Diameter (mm)	50.8 ± 0.3	76.0 ± 0.5	100 ± 0.5	125 ± 0.5	150 ± 0.5
Orientation	<111>	<111>	<111>	<111>	<111>
Thickness (μm)	100 to 25000	150 to 25000	200 to 25000	250 to 5000	350 to 5000
Thickness tolerance (μm)					
Standard	± 25	± 25	± 25	± 25	± 25
Typical	± 10	± 10	± 15	± 20	± 25
Total thickness variation TTV max	10	15	15	20	25

TRANSMISSION SPECTRUM (high resistivity Si)



RECOMMENDED APPLICATIONS

Wafer Resistivity (ohm.cm)	< 0.05	1 - 5	6 - 12	> 30
Application	Epitaxial substrate	Solar cell	IC, OE devices or sensors	Special device or component

THERMAL OXIDATION

On request, a thermal oxidation can be grown on our Silicon wafers.

- Oxidation thickness: 100 nm to max. 2 μm .
- Wafer sizes: up to 4".

OTHER SERVICE

We can make special vacuum coatings on wafers: for example, we can deposit a pre-coating of Chromium or Titanium before a thin film of Gold, or any other evaporated or sputtered material. Contact us for your specific needs.

Single Crystal Substrates

Sapphire Al_2O_3 substrate	J 08	Magnesium Aluminum Oxide MgAl_2O_4 substrate	J 27
Barium Fluoride BaF_2 substrate	J 09	Magnesium Fluoride MgF_2 substrate	J 28
Barium Titanate BaTiO_3 substrate	J 10	Magnesium Oxide MgO substrate	J 29
Calcium Fluoride CaF_2 substrate	J 11	Manganese Oxide MnO substrate	J 30
Calcium Neodymium Aluminate		Sodium Chloride NaCl substrate	J 31
CaNdAlO_4 (CNAO) substrate	J 12	Neodymium Gallate NdGaO_3 (NGO) substrate	J 32
Cadmium Sulfide CdS substrate	J 13	Nickel Oxide NiO substrate	J 32
Cadmium Selenide CdSe substrate	J 13	Quartz SiO_2 substrate	J 33
Cadmium Telluride CdTe substrate	J 14	Strontium Lanthanum Aluminate	
Cobalt Oxide CoO substrate	J 15	SrLaAlO_4 substrate	J 34
Chromium Oxide Cr_2O_3 substrate	J 15	Strontium Lanthanum Gallate	
Gallium Arsenide GaAs substrate	J 16	$\text{SrLaGa}_3\text{O}_7$ substrate	J 34
Gallium Phosphide GaP substrate	J 17	Strontium Lanthanum Gallate	
Gadolinium Gallium Garnet $\text{Gd}_3\text{Ga}_5\text{O}_{12}$		SrLaGaO_4 substrate	J 35
(GGG) substrate	J 18	Strontium Titanate SrTiO_3 substrate	J 36
Germanium Ge substrate	J 19	Titanium Oxide (Rutile) TiO_2 substrate	J 37
Indium Arsenide InAs substrate	J 20	Yttrium Aluminium Garnet $\text{Y}_3\text{Al}_5\text{O}_{12}$	
Indium Phosphide InP substrate	J 21	(YAG) substrate	J 38
Lanthanum Aluminate LaAlO_3 substrate	J 22	Yttrium Aluminate YAlO_3 (YAP) substrate	J 39
Lithium Aluminate LiAlO_2 substrate	J 23	Yttria Stabilized Zirconia (YSZ) substrate	J 39
Lithium Fluoride LiF substrate	J 23	Zinc Oxide ZnO substrate	J 40
Lithium Gallate LiGaO_2 substrate	J 25	Zinc Sulfide ZnS substrate	J 41
Lithium Niobate LiNbO_3 substrate	J 25	Zinc Selenide ZnSe substrate	J 42
Lithium-Strontium-Aluminum-Tantalum-Oxide		Zinc Telluride ZnTe substrate	J 43
(LSAT) substrate	J 26		

SAPPHIRE Al_2O_3 SUBSTRATE

Sapphire (single crystal of Al_2O_3) is being used extensively as a substrate for III-V nitrides and for many other epitaxial films. Single crystal sapphire wafer plays an increasingly important role as a material for blue LED, high Tc superconductor and microwave applications, due to its high strength, high anti-corrosion, high anti-abrasion, low dielectric loss and good electrical insulation.

NEYCO provides sapphire substrates with complete orientation options including C plane, A plane, R plane and M plane, in diameter range from 1" to 4", square substrate is also available as well, size from 10 x 10 mm to 100 x 100 mm. NEYCO can offer EPI ready grade sapphire wafer for your epitaxial growth.

FEATURES

- High working temperature
- Good thermal conductivity
- Superior mechanical properties
- High anti corrosion
- Stable dielectric constant & low dielectric loss
- Excellent light transmission

APPLICATIONS

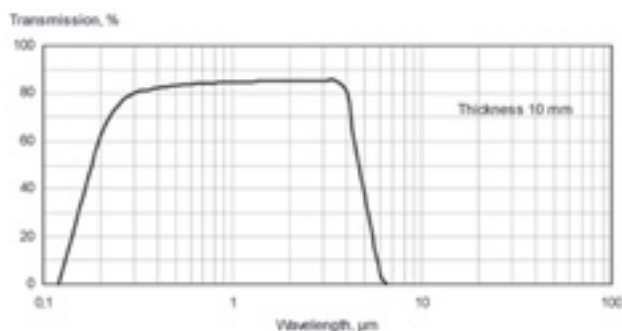
- Blue LED substrate
- Superconductor substrate
- Electronics and optoelectronics
- UV and IR optics

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 4"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal $a = 0.477 \text{ nm}$ $c = 1.304 \text{ nm}$
Color	Colourless
PHYSICAL PROPERTIES	
Density	3.98 g.cm^{-3}
Melting point	2052°C
Hardness	9 Mohs
Thermal expansion	Vertical c-axis: $6.2 \cdot 10^{-6} \text{ K}^{-1}$ Parallel c-axis: $5.4 \cdot 10^{-6} \text{ K}^{-1}$
Thermal conductivity	Vertical c-axis: $23.1 \text{ W.m}^{-1}.\text{K}^{-1}$ Parallel c-axis: $25.2 \text{ W.m}^{-1}.\text{K}^{-1}$
Heat capacity	$761 \text{ J.kg}^{-1}.\text{K}^{-1}$
Dielectric constant	Vertical c-axis: 9.4 Parallel c-axis: 11.5
Loss Tangent at 10 GHz	Vertical c-axis: $8.6 \cdot 10^{-8}$ Parallel c-axis: $3 \cdot 10^{-8}$
CHEMICAL PROPERTIES	
Solubility in water	$98 \cdot 10^{-6} \text{ g/100 cm}^3$
Solubility in acids	Insoluble
Solubility in organic solvents	Not declare

OPTICAL PROPERTIES				
Absorption coefficient	0.2 cm ⁻¹ at 0.2 μm 0.02 cm ⁻¹ at 0.4 μm 0.46 cm ⁻¹ at 5 μm			
Transmission range (thickness 10 mm)	0.17 – 5.0 μm			
Refractive index n	1 μm	2 μm	3 μm	4 μm
	1.7545	1.7374	1.7015	1.6748

TRANSMISSION SPECTRUM



BARIUM FLUORIDE BaF₂ SUBSTRATE

APPLICATIONS

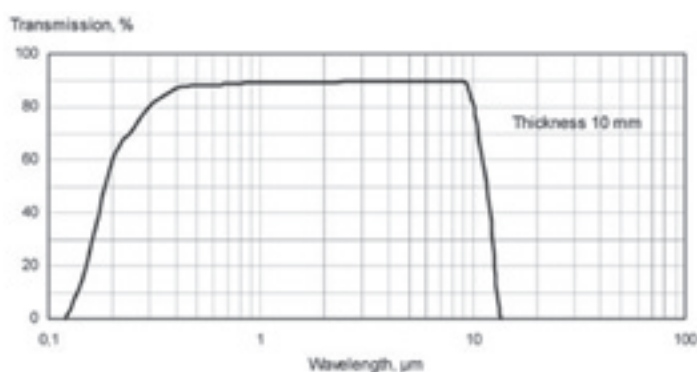
IR and UV window, prism, substrate.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Stockbarger technique
Maximum size	Ø 150 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.6196 nm
Cleavage plane	<111>
PHYSICAL PROPERTIES	
Density	4.83 g.cm ⁻³
Melting point	1354°C
PHYSICAL PROPERTIES	
Hardness	3 Mohs
Thermal expansion	16.5 - 19.2 x 10 ⁻⁶ K ⁻¹

PHYSICAL PROPERTIES						
Thermal conductivity	7.1 W.m ⁻¹ .K ⁻¹					
Specific heat capacity	456 J.kg ⁻¹ .K ⁻¹					
CHEMICAL PROPERTIES						
Solubility in water	0.17 g/100 cm ³					
Solubility in acids	Soluble					
Solubility in organic solvents	Not declare					
OPTICAL PROPERTIES						
Absorption coefficient	0.20 cm ⁻¹ at 0.2 μm 0.08 cm ⁻¹ at 0.4 μm 0.13 cm ⁻¹ at 10.6 μm					
Refractive index n	0.2 μm	0.5 μm	1.0 μm	5.0 μm	10.0 μm	12.0 μm
	1.5573	1.4779	1.4686	1.4511	1.4014	1.3696

TRANSMISSION SPECTRUM



BARIUM TITANATE BaTiO₃ SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	10 x 10 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal a = 0.3992 nm c = 0.4036 nm
PHYSICAL PROPERTIES	
Density	8.82 g.cm ⁻³
Melting point	1600°C
Hardness	5 Mohs

CALCIUM FLUORIDE CaF_2 SUBSTRATE

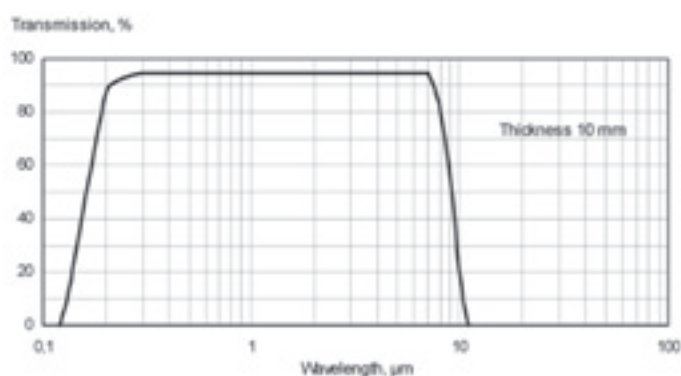
APPLICATIONS

IR windows and lens, prism.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH						
Growth method	Stockbarger technique					
Maximum size	Ø 200 mm					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Cubic a = 0.5462 nm					
Cleavage plane	<111>					
PHYSICAL PROPERTIES						
Density	3.18 g.cm ⁻³					
Melting point	1418°C					
Hardness	4 Mohs					
Thermal expansion	16.2 - 19.4 x 10 ⁻⁶ K ⁻¹					
Thermal conductivity	9.17 W.m ⁻¹ .K ¹					
Specific heat capacity	888 J.kg ⁻¹ .K ⁻¹					
CHEMICAL PROPERTIES						
Solubility in water	0.0016 g/ 100 cm ³					
Solubility in acids	Unessential					
Solubility in organic solvents	Insoluble in acetone					
OPTICAL PROPERTIES						
Transmission range (Thickness 10 mm)	0.15 - 9.0 µm					
OPTICAL PROPERTIES						
Refractive index	0.2 µm	0.5 µm	1.0 µm	5.0 µm	10.0 µm	12.0 µm
	1.4951	1.4365	1.4289	1.3990	1.3002	1.2299
Absorption coefficient	0.10 cm ⁻¹ at 0.2 µm 0.01 cm ⁻¹ at 0.4 µm 0.03 cm ⁻¹ at 2.6-2.9 µm					

TRANSMISSION SPECTRUM



CALCIUM NEODYMIUM ALUMINATE CaNdAlO₄ (CNAO) SUBSTRATE

MATERIAL CHARACTERISTICS

High quality YBaCuO, BiSrCaCuO, Bi(Pb)CaCuO and TlBaCaCuO thin films have been grown on CaNdAlO₄ substrates by different techniques.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 18 - 20 mm
Standard thickness	0.5 to 1 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal a = 0.369 nm c = 2.215 nm
Color	Violet
Twin structure	No
PHYSICAL PROPERTIES	
Density	5.527 g.cm ⁻³
Melting point	1860°C
Thermal expansion	Along a-axis: 8.67.10 ⁻⁶ K ⁻¹ Along c-axis: 1.57.10 ⁻⁵ K ⁻¹
Dielectric constant	20
Loss tangent (at 10 GHz)	2.10 ⁻³
OPTICAL PROPERTIES	
Transmission range	220 to 6670 nm (excluding Nd range)
Refractive index n	1.941

CADMIUM SULFIDE CdS SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Seeded vapour phase growth
Maximum size	Ø 50 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal a = 0.4135 nm c = 0.6749 nm
PHYSICAL PROPERTIES	
Density	4.82 g.cm ⁻³
Melting point	1475°C
Hardness	4 Mohs
Thermal expansion	4.2.10 ⁻⁶ K ⁻¹
Resistivity range	> 10 ⁸ Ω.cm (high resistivity) < 10 ¹ Ω.cm (low resistivity)
Band gap at 300 K	2.53 eV
Thermal conductivity	15.9 W.m ⁻¹ .K ⁻¹
Conductivity type	N-type
Carrier concentration	10 ⁹ - 10 ¹⁸ cm ⁻³
Dielectric constant	Vertical c-axis: 8.28 Parallel c-axis: 8.64

CADMIUM SELENIDE CdSe SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Seeded vapour phase growth
Maximum size	Ø 50 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal a = 0.431 nm c = 0.7021nm
PHYSICAL PROPERTIES	
Density	5.816 g.cm ⁻³
Melting point	1268°C
Hardness	4 Mohs
Thermal expansion	2.9.10 ⁻⁶ K ⁻¹
Resistivity range	> 10 ⁷ Ω.cm (high resistivity) < 10 ¹ Ω.cm (low resistivity)
Thermal conductivity	3.49 W.m ⁻¹ .K ⁻¹
Band gap at 300 K	1.74 eV
Conductivity type	N-type

CADMIUM TELLURIDE CdTe SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH						
Growth method	Modified Bridgman (with Cd-reservoir)					
Maximum size	Ø 60 mm					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Cubic a = 0.6481 nm					
Cleavage	<110>					
PHYSICAL PROPERTIES						
Density	5.855 g.cm ⁻³					
Melting point	1092°C					
Hardness	3 Mohs					
Thermal expansion	5.7.10 ⁻⁶ K ⁻¹					
Thermal conductivity	6.28 W.m ⁻¹ .K ⁻¹					
Resistivity range	> 10 ⁹ Ω.cm					
Band gap at 300 K	1.5 eV					
Conductivity type	N-type, P-type					
CHEMICAL PROPERTIES						
Solubility in water	Insoluble					
Solubility in acids	Insoluble					
Solubility in organic solvents	Insoluble					
OPTICAL PROPERTIES						
Absorption coefficient	0.001 cm ⁻¹ at 10.6 μm					
Transmission range (thickness 2 mm)	0.9 μm to 24 μm					
Refractive index n	1 μm	5 μm	10 μm	15 μm	20 μm	30 μm
	2.831	2.692	2.679	2.659	2.632	2.559

COBALT OXIDE CoO SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Verneuil
Maximum size	Ø 15mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.4267 nm
Color	Black
PHYSICAL PROPERTIES	
Density	6.4 g.cm ⁻³
Melting point	1935°C
Hardness (Knoop test)	310 to 345

CHROMIUM OXIDE Cr₂O₃ SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Verneuil
Maximum size	Ø 15 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal a = 0.496 nm c = 1.3599 nm
Color	Black
PHYSICAL PROPERTIES	
Density	5.2 g.cm ⁻³
Melting point	2275°C

GALLIUM ARSENIDE GaAs SUBSTRATE

Gallium Arsenide used for lenses and beam splitters provides an alternative to ZnSe in medium and high power CW CO₂ laser systems. It is most useful in applications where toughness and durability are important. Its hardness and strength make it a good choice where dust or

abrasive particles tend to build up on or bombard the optical surfaces. When frequent cleaning by wiping is required, GaAs is excellent. The material is nonhygroscopic, safe to use in laboratory and field conditions and is chemically stable except when in contact with strong acids.

FEATURES

- High mobility
- High frequency
- Low power consumption

APPLICATIONS

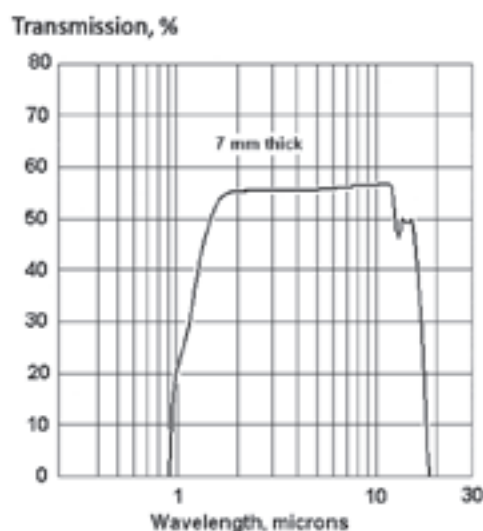
- Visible and infrared LED
- Light emitting diodes
- Laser diodes

STANDARD SPECIFICATIONS

CRYSTAL GROWTH										
Growth method	Czochralski (CZ) or Vertical Gradient Freeze									
Maximum size	Ø 4"									
Standard thickness	350 - 625 µm									
CRYSTALLOGRAPHIC PROPERTIES										
Crystal structure	Cubic a = 0.565 nm									
Dopant available	Silicon, Tellurium, Zinc, Chromium									
PHYSICAL PROPERTIES										
Density	5.32 g.cm ⁻³									
Melting point	1238°C									
Hardness (Knoop test)	750									
Thermal expansion	5.8.10 ⁻⁶ K ⁻¹									
Dielectric constant	12.85									
Band gap	1.42 eV									
Thermal conductivity	0.55 W.cm ⁻¹ .K ⁻¹									
Specific heat capacity	0.327 J.g ⁻¹ .K ⁻¹									
Conductivity	Semi-conducting or semi-insulating									
Conductivity type	P-type or N-type									
OPTICAL PROPERTIES										
Absorption coefficient	< 0.02 cm ⁻¹ at 10.6 µm									
Transmission range (thickness 7 µm)	1.0 to 22 µm									
Solubility in water	None									
Refractive index n	8 µm	10 µm	11 µm	13 µm	13.7 µm	14.5 µm	15 µm	17 µm	19 µm	21.9 µm
	3.34	3.13	3.04	2.97	2.89	2.82	2.73	2.59	2.41	2.12

Parameters	Undoped GaAs	Si Doped GaAs	Zn Doped GaAs	Cr Doped GaAs	Te Doped GaAs
Doping	Undoped	Si	Zn	Cr	Te
Conductor type	N, (SI)	N	P	SI	N
Carrier concentration (cm ⁻³)	-	(5 - 15).10 ¹⁷	> 5.10 ¹⁸	-	5 - 20.10 ¹⁷
Resistivity (Ω.cm)	> 1.10 ⁻⁷	-	-	> 5.10 ⁷	-
Mobility (cm ² .V ⁻¹ .s ⁻¹)	> 4500	3000 - 1800	> 50	> 3000	> 1500
E.P.D. (cm ⁻²)	< 5.10 ⁴	1.10 ⁴ - 3.10 ³	< 5.10 ⁴	> 8.10 ⁴	< 3000

TRANSMISSION SPECTRUM



GALLIUM PHOSPHIDE GaP SUBSTRATE

GaP single crystals are grown by the Czochralski technique and are widely used for red, yellow and green LED substrates. NEYCO provides high quality as-cut GaP

wafers for LPE in mass production, and also supplies EPI polished wafers for CVD and MBE applications.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 2"
Standard thickness	500 µm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.357 nm
PHYSICAL PROPERTIES	
Conductivity	Semi-conducting (SI)
Conductivity type	N-type
Dopant available	Silicon

Dopant	Si doped	Undoped
Carrier concentration	$2 - 8 \cdot 10^{17} \text{ cm}^{-3}$	$4 - 6 \cdot 10^{16} \text{ cm}^{-3}$
EPD	$< 3 \cdot 10^5 \text{ cm}^{-2}$	$< 3 \cdot 10^5 \text{ cm}^{-2}$
Resistivity range	$\sim 0.03 \text{ } \Omega \cdot \text{cm}$	$\sim 0.3 \text{ } \Omega \cdot \text{cm}$
Density	$4.13 \text{ g} \cdot \text{cm}^{-3}$	
Melting point	1480°C	
Thermal expansion	$5.3 \cdot 10^{-6} \text{ K}^{-1}$	
Band gap	2.26 eV	
Thermal conductivity	$1.1 \text{ W} \cdot \text{cm}^{-1} \cdot \text{K}^{-1} \text{ at } 300 \text{ K}$	

GADOLINIUM GALLIUM GARNET $\text{Gd}_3\text{Ga}_5\text{O}_{12}$ (GGG) SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	$\varnothing 3''$
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic $a = 1.2382 \text{ nm}$
Color	Pale yellow
PHYSICAL PROPERTIES	
Density	$7.02 \text{ g} \cdot \text{cm}^{-3}$
Melting point	1730°C
Thermal expansion	$9.7 \cdot 10^{-6} \text{ K}^{-1}$

GERMANIUM Ge SUBSTRATE

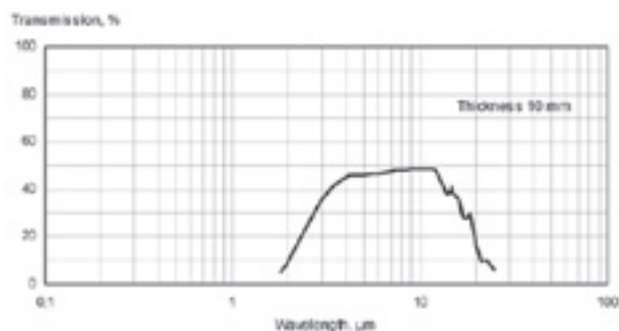
APPLICATIONS

- IR optics
- Solar cell application
- Optical fiber production
- Semiconductor and electronics device

STANDARD SPECIFICATIONS

CRYSTAL GROWTH						
Growth method	Czochralski (CZ)					
Maximum size	Ø 3"					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Cubic a = 0.565 nm					
Dopant available	Antimony (N), Gallium (P)					
Cleavage	<111>					
PHYSICAL PROPERTIES						
Density	5.32 g.cm ⁻³					
Melting point	937°C					
Hardness	6 Mohs					
Thermal expansion	5.75.10 ⁻⁶ K ⁻¹					
PHYSICAL PROPERTIES						
Resistivity range	N-type: < 0.4 Ω.cm P-type: 0.005 - 30 Ω.cm Undoped: > 30 Ω.cm					
Specificity heat capacity	310 J.kg ⁻¹ .K ⁻¹					
Band gap at 273 K	0.67 eV					
Thermal conductivity	58.6 W.m ⁻¹ .K ⁻¹					
Carrier mobility	μ _e = 3900 cm ² .V ⁻¹ .s ⁻¹ μ _h = 1900 cm ² .V ⁻¹ .s ⁻¹					
Conductivity type	P-type or N-type					
CHEMICAL PROPERTIES						
Solubility in water	Insoluble					
Solubility in acids	Soluble in mixture of HCl and HNO ₃ and H ₂ O ₂					
Solubility in organic solvents	Insoluble					
OPTICAL PROPERTIES						
Absorption coefficient	0.02 cm ⁻¹ at 10.6 μm					
Transmission range (thickness 10 mm)	2 to 18 μm					
Refractive index n	2.0 μm	5.0 μm	8.0 μm	10.0 μm	11.0 μm	15.0 μm
	4.1079	4.0153	4.0053	4.0040	4.0031	4.0017

TRANSMISSION SPECTRUM



INDIUM ARSENIDE InAs SUBSTRATE

NEYCO provides InAs wafers (Indium Arsenide) to optoelectronics in diameter up to 2 inch. InAs crystal has high uniformity of electrical parameters and low defect density, suitable for MBE or MOCVD epitaxial growth.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 2"
Standard thickness	500 μm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic
PHYSICAL PROPERTIES	
Band gap	0.4 eV
Conductivity	Semi-conducting (SI)
Conductivity type	P-type or N-type
Dopant available	Silicon, Zinc

DOPANT AVAILABLE	TYPE	CARRIER CONCENTRATION (cm ⁻³)	MOBILITY (cm ² .V ⁻¹ .s ⁻¹)
Undoped	N	-	> 20000
Si	N	1.10 ¹⁷ - 3.10 ¹⁸ cm ⁻³	10000 - 25000
Zn	P	1.10 ¹⁷ - 5.10 ¹⁸ cm ⁻³	100 - 500

INDIUM PHOSPHIDE InP SUBSTRATE

NEYCO supplies high quality InP single crystal substrates for semiconductor industries. The wafers are cut along precise orientation and highly EPI polished.

APPLICATIONS

InP has been a focus of development since the early 1980s, and today the material is being used as a platform for a wide variety of fiber communications components, including lasers, LEDs, semiconductor optical amplifiers, modulators and photo-detectors.

InP applications for discrete active devices are widespread in communications networking, making it the natural starting place for wholesale integration of passive devices for a complete system on a chip. As a semiconductor material, InP can provide all-in-one integrated functionality that includes light generation, detection, amplification, high-speed modulation and switching, as well as passive splitting, combining and routing. The same material can be used to make high-speed modulators, switches, amplifiers and detectors, or just passive wave guides for interconnecting these diverse devices.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Standard thickness	500 μm
Maximum size	\varnothing 2"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Face-centered cubic (Zinc blende)
PHYSICAL PROPERTIES	
Band gap	1.344 eV
Conductivity	Semi-conducting or semi-insulating (SI)
Conductivity type	P-type or N-type
Dopant available	Silicon, Tin, Zinc, Iron
Density	4.81 g.cm^{-3}
Melting point	1082°C
Thermal conductivity	0.68 $\text{W.cm}^{-1}.\text{K}^{-1}$ at 300 K

DOPANT AVAILABLE	TYPE	CARRIER CONCENTRATION (cm^{-3})	MOBILITY ($\text{cm}^2 . \text{V}^{-1} . \text{s}^{-1}$)	RESISTIVITY ($\Omega . \text{cm}$)	EPD (cm^{-2})
Undoped	N	0.8 - 2.0 $\cdot 10^{15}$	3600 - 4000	0.03 - 0.2	5-6 $\cdot 10^4$
Sn, Si	N	0.5 - 1.0 $\cdot 10^{18}$	200 - 2400	0.001 - 0.002	3-5 $\cdot 10^4$
		0.5 - 1.0 $\cdot 10^{18}$	1500 - 2000	0.0025 - 0.007	
Zn	P	0.8 - 2.0 $\cdot 10^{18}$	2500 - 3500	0.0025 - 0.006	1-3 $\cdot 10^4$
		2.5 - 4.0 $\cdot 10^{18}$	1300 - 1600		
Fe	SI	0.1 - 1.0	2000	10 ⁷ - 10 ⁸	4-5 $\cdot 10^4$

LANTANUM ALUMINATE LaAlO_3 SUBSTRATE

LaAlO_3 single crystal provides a good lattice match to many materials with perovskite structure. It is an excellent substrate for epitaxial growth of high T_c superconductors,

magnetic and ferro-electric thin films. The dielectric properties of LaAlO_3 crystal are well suitable for low loss microwave and dielectric resonance applications.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Max. size	Ø 3"
Standard thickness	0.5 to 1 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Rhombohedral at 25°C $a = 0.5357 \text{ nm}$
	Cubic at > 435°C $a = 0.379 \text{ nm}$
Twin structure	Twins // to the <100>-planes of the pseudocubic cell
Color	Tan to brown based on annealing condition
PHYSICAL PROPERTIES	
Density	6.52 g.cm^{-3}
Melting point	2180°C
Thermal expansion	$9.2 \cdot 10^{-6} \text{ K}^{-1}$
Dielectric constant	24.5
Loss tangent (at 10 GHz)	~ $3 \cdot 10^{-4}$ at 300 K ~ $6 \cdot 10^{-5}$ at 77 K
CHEMICAL PROPERTIES	
Chemical stability	Insoluble in mineral acids at 25°C and soluble in H_3PO_3 at > 150°C

LITHIUM ALUMINATE LiAlO_2 SUBSTRATE

LiAlO_2 is a potential substrate for III-V nitride thin films due to its excellent lattice mismatch to GaN (<0.2% at <100>), chemical stability at high temperature and cost effective.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 2"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal a = 0.517 nm c = 0.626 nm
Color	Transparent
PHYSICAL PROPERTIES	
Density	2.2 g.cm ⁻³
Melting point	1900°C
Hardness	7.5 Mohs

LITHIUM FLUORIDE LiF SUBSTRATE

APPLICATION

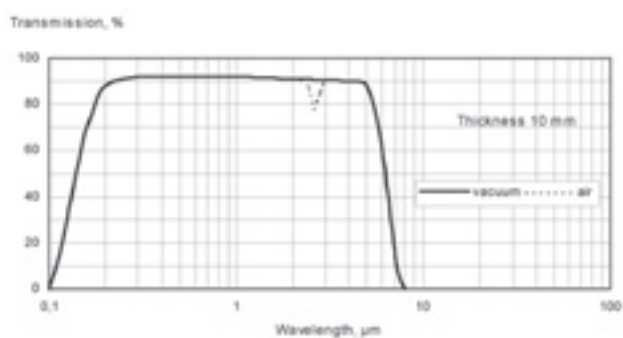
UV window and prism, without deliquescence.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Stockbarger technique
Maximum size	Ø 150 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.4026 nm
Cleavage plane	<100>
PHYSICAL PROPERTIES	
Density	2.60 g.cm ⁻³
Melting point	870°C

PHYSICAL PROPERTIES						
Hardness	4 Mohs					
Thermal expansion	28.1 - 34.8.10 ⁻⁶ K ⁻¹					
Thermal conductivity	14.2 W.m ⁻¹ .K ⁻¹					
Specific heat capacity	1562 J.kg ⁻¹ .K ⁻¹					
CHEMICAL PROPERTIES						
Solubility in water	0.27 g/100 cm³					
Solubility in acids	Soluble					
Solubility in organic solvents	Insoluble in acetone and ethylalcohol					
OPTICAL PROPERTIES						
Absorption coefficient	0.05 cm ⁻¹ at 0.2 μm 0.02 cm ⁻¹ at 0.4 μm 0.03 cm ⁻¹ at 2.6-2.9 μm					
Transmission range (thickness 10 mm)	0.12 - 6.5 μm					
Refractive index n	0.2 μm	0.5 μm	1.0 μm	3.0 μm	5.0 μm	6.0 μm
	1.4390	1.3943	1.3871	1.3666	1.3266	1.2975

TRANSMISSION SPECTRUM



LITHIUM GALLATE LiGaO_2 SUBSTRATE

LiGaO_2 single crystal was grown in 1960's for laser application. However, it is found out that LiGaO_2 is a potential substrate for III-V nitride thin films due to its excellent lattice mismatch to GaN (<0.2%), chemical stability at high temperature and cost effective.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 20 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Orthorhombic a = 0.54 nm b = 0.6379 nm c = 0.5012 nm
Color	White to brown
Twin structure	No twins and inclusion
PHYSICAL PROPERTIES	
Density	4.18 g.cm ⁻³
Melting Point	1600°C

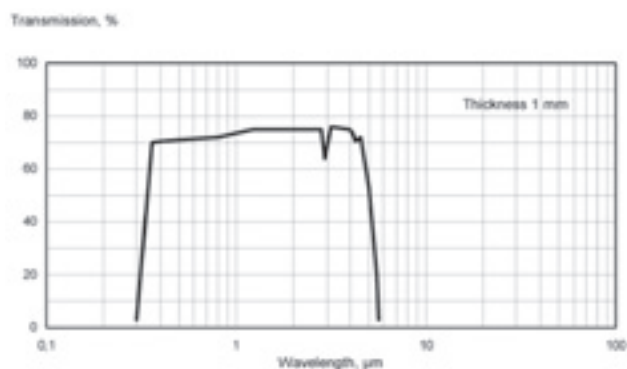
LITHIUM NIOBATE LiNbO_3 SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal a = 0.5148 nm c = 1.3863 nm
PHYSICAL PROPERTIES	
Density	4.64 g.cm ⁻³
Melting point	1250°C
Hardness	5 Mohs
Thermal expansion	Vertical c-axis: $15.4 \cdot 10^{-6} \text{ K}^{-1}$ Parallel c-axis: $7.5 \cdot 10^{-6} \text{ K}^{-1}$

OPTICAL PROPERTIES			
Transmission range	0.4 - 2.90 μm		
Refractive index:	0.633 μm	1.064 μm	1.30 μm
n_o	2.286	2.232	2.220
n_e	2.203	2.156	2.146

TRANSMISSION SPECTRUM



LANTHANUM-STRONTIUM-ALUMINUM-TANTALUM-OXIDE (LSAT) SUBSTRATE

LSAT (LaAlO_3)_{0.3}($\text{Sr}_2\text{AlTaO}_6$)_{0.7} is a newly developing crystal with perovskite structure and twin-free. LSAT has excellent lattice match with high T_c superconductors and many oxide materials. LSAT has lower melting point and can be grown by CZ technology at lower cost, therefore,

it is expected to replace LaAlO_3 and SrTiO_3 as a common single crystal substrate for epitaxial oxide thin films for gain magnetic ferro-electronic and superconductive devices.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	$\varnothing 2''$
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic $a = 0.7737 \text{ nm}$
Twin structure	No twin and domain visible
Color	Colorless to light brown based on annealing condition
PHYSICAL PROPERTIES	
Density	6.74 g.cm^{-3}
Melting point	1840°C

PHYSICAL PROPERTIES	
Thermal expansion	$10 \cdot 10^{-6} \text{ K}^{-1}$
Dielectric constant	~ 22
Loss tangent (at 8.8 GHz)	$2 \cdot 10^{-4}$ at 77 K

MAGNESIUM ALUMINUM OXIDE MgAl_2O_4 SUBSTRATE

MgAl_2O_4 (spinel) single crystals are widely used for bulk acoustic wave and microwave devices and fast IC epitaxial substrates. It is also found that MgAl_2O_4 is a good

substrate for III-V nitrides device. MgAl_2O_4 crystal is very difficult to grow, due to the difficulty in maintaining a single phase structure.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	$\varnothing 30 \text{ mm}$
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic $a = 0.8083 \text{ nm}$
Color	Colourless
PHYSICAL PROPERTIES	
Density	3.64 g.cm^{-3}
Melting Point	2130°C
Hardness	8.0 Mohs
Thermal expansion	$7 \cdot 10^{-6} \text{ K}^{-1}$

MAGNESIUM FLUORIDE MgF₂ SUBSTRATE

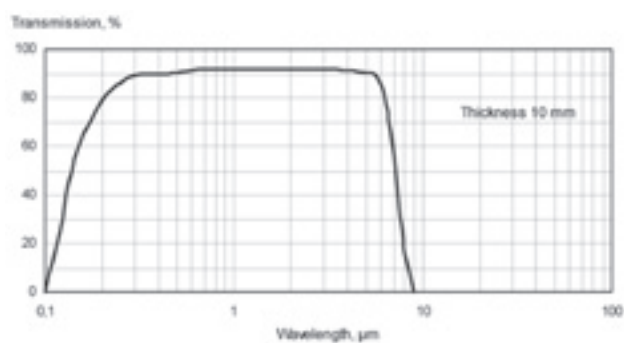
APPLICATIONS

VUV window and mirror, lens.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH						
Growth method	Stockbarger technique					
Cleavage	<100>, <110>					
Maximum size	Ø 90 mm					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Tetragonal a = 0.464 nm c = 0.306 nm					
PHYSICAL PROPERTIES						
Density	3.18 g.cm ⁻³					
Melting point	1255°C					
Hardness	6 Mohs					
Thermal expansion	Parallel c-axis: 10.86 - 14.54.10 ⁻⁶ K ⁻¹ Vertical c-axis: 6.23 - 9.25.10 ⁻⁶ K ⁻¹					
Specific heat capacity	920 J.kg ⁻¹ .K ⁻¹					
CHEMICAL PROPERTIES						
Solubility in water	0.0076 g/100 cm ³					
Solubility in acids	Soluble					
Solubility in organic solvents	Insoluble in alcohol					
OPTICAL PROPERTIES						
Absorption coefficient (cm ⁻¹)	0.07 cm ⁻¹ at 0.2 µm 0.02 cm ⁻¹ at 5.0 µm					
Refractive index:	0.2 µm	0.5 µm	1.0 µm	3.0 µm	5.0 µm	7.0 µm
n _o	1.4231	1.3797	1.3736	1.3618	1.3400	1.3044
n _e	1.4367	1.3916	1.3852	1.3724	1.3487	1.3101

TRANSMISSION SPECTRUM



MAGNESIUM OXIDE MgO SUBSTRATE

MgO is an excellent single crystal substrate for thin films of ferro-magnetic, photo-electronic and high Tc superconductor materials.

FEATURES

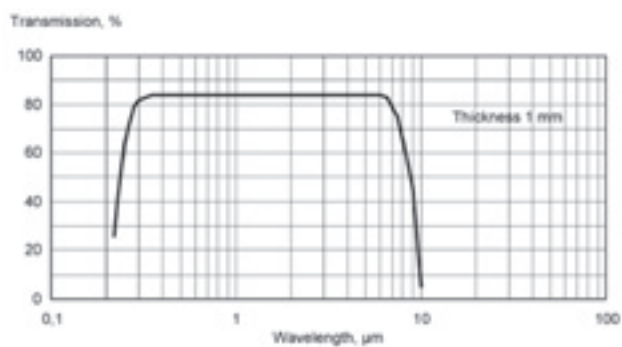
- Low dielectric loss
- Cleavage plane on the <100>

APPLICATIONS

- High Tc Superconductor
- Electronics and optoelectronics
- Microwave device

STANDARD SPECIFICATIONS

CRYSTAL GROWTH				
Growth method	Flux melt			
Standard thickness	0.5 to 1 mm			
Maximum size	Ø 2"			
CRYSTALLOGRAPHIC PROPERTIES				
Crystal structure	Cubic a = 0.4216 nm			
Cleavage	<100>			
Twin structure	Without twins			
Color	Colorless			
PHYSICAL PROPERTIES				
Density	3.58 g.cm ⁻³			
Melting point	2800°C			
Hardness	5.8 Mohs			
Thermal expansion	8.10 ⁻⁶ K ⁻¹			
Thermal conductivity	40.6 W.m ⁻¹ K ⁻¹			
Specific heat capacity	837 J.kg ⁻¹ .K ⁻¹			
Dielectric constant	8.1			
Loss tangent (at 10 GHz)	~ 9.10 ⁻³ at 77 K			
CHEMICAL PROPERTIES				
Chemical stability	Insoluble in mineral acids at 25 °C and soluble in H ₃ PO ₃ at > 150 °C			
Solubility in water	0.00062 g/100 cm ³			
OPTICAL PROPERTIES				
Transmission range (thickness 1 mm)	0.3 - 7.0 μm			
Refractive index n	0.5 μm	1 μm	3 μm	5 μm
	1.74	1.72	1.68	1.63

TRANSMISSION
SPECTRUM

MANGANESE OXIDE MnO SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Verneuil
Maximum size	Ø 15 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic $a = 0.4445 \text{ nm}$
Color	Black
PHYSICAL PROPERTIES	
Density	5.4 g.cm^{-3}
Melting point	1650°C
Hardness (Knoop test)	300

SODIUM CHLORIDE NaCl SUBSTRATE

Use only these crystals for fine research work requiring minimum 10 mm square uninterrupted areas.

- Formula: NaCl
- Appearance: Cubic clear (nearly transparent) crystals
- Density: 2.165 g.cm⁻³
- Solubility in water: a thin “wafer” that is 0.05” (1.27 mm) will dissolve in water at room temperature in roughly 30 seconds

GROW EPITAXIAL FILMS

These high quality research grade sodium chloride single crystal substrates offer a major advantage: the ability to grow epitaxial films on a featureless substrate.

The orientation of the film is related to the orientation of the substrate, producing areas of single crystal film.

This feature is ideal for boundary diffusion studies and applications where a single crystal thin film is required. The film is easily removed by floating it off on water or by dissolving away the underlying substrate.

SIZES	PACKAGING	P/N
25 mm cubes	1	01817-AB
10 mm cubes	5	01807-AF
25 mm cubes	5	01817-AF

OFF-CUTS

- Use for class experiments and for the teaching of cleaving techniques
- Approximate size range: 20 mm to 45 mm
- Note: Some “fines” will be present as well

PACKAGING	P/N
100 g	01779-AB

NEODYMIUM GALLATE NdGaO₃ (NGO) SUBSTRATE

MATERIAL CHARACTERISTICS

- Excellent lattice matches to the typical HTSC composition
- Low dielectric constant and low dielectric loss tangent, which makes it attractive for microwave applications
- Good thermal properties
- No destructive phase transformations

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 2"
Standard thickness	0.5 to 1 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Orthorhombic to > 1000°C a = 0.5426 nm b = 0.5496 nm c = 0.7707 nm Second order phase transformation at 950°C
Twin structure	Without twins
Color	Deep red to green
PHYSICAL PROPERTIES	
Density	7.56 g.cm ⁻³
Melting point	1750°C
Hardness	5.9 Mohs
Thermal expansion	11.10 ⁻⁶ K ⁻¹
Dielectric constant (1 MHz)	20 at 300 K

NICKEL OXIDE NiO SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Verneuil
Maximum size	Ø 15 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.419 nm
Color	Black
PHYSICAL PROPERTIES	
Density	6.96 g.cm ⁻³
Melting point	1998°C
Hardness (Knoop test)	560 - 590

QUARTZ SiO₂ SUBSTRATE

FEATURES

- High working temperature
- Good thermal conductivity
- High stability
- High anti corrosion
- Superior mechanical properties
- Stable dielectric constant & low dielectric loss
- High optical transmission

APPLICATIONS

- Photo mask blank
- Sensors
- High frequency circuit (Microwave circuit)
- Biotech arrays
- Laser Optics
- Optical windows and lenses

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Hydrothermal synthesis
Maximum size	100 x 100 mm
Standard thickness	0.5 mm to 4 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal a = 0.490 nm c = 0.539 nm
Color	Colourless
PHYSICAL PROPERTIES	
Density	2.65 g.cm ⁻³
Melting Point	1700°C
Hardness	5.5 - 6.5 Mohs
Thermal expansion	Vertical c-axis: 13.37.10 ⁻⁶ K ⁻¹ Parallel c-axis: 7.97.10 ⁻⁶ K ⁻¹
Resistivity	7.10 ⁷ Ω.cm
Dielectric constant	3.7 - 3.9

STRONTIUM LANTHANUM ALUMINATE SrLaAlO_4 SUBSTRATE

SrLaAlO_4 crystal is a promising substrate material for high T_c superconductor film and other oxide films. It has similar lattice constant to SrTiO_3 , but better quality and lower cost because of CZ growth and lower melting point.

APPLICATIONS

High quality YBaCu , BiSrCaCuO , Bi(Pb)CaCuO and TlBaCaCuO thin films have been grown on SrLaAlO_4 substrates by different techniques.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 18 - 20 mm
Standard thickness	0.5 to 1 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal $a = 0.3754 \text{ nm}$ $c = 1.2630 \text{ nm}$
Twin structure	No
Color	Light yellow
PHYSICAL PROPERTIES	
Density	5.924 g.cm^{-3}
Melting point	1650°C
Hardness	7 Mohs
Thermal expansion	Along a-axis: $7.55 \cdot 10^{-6} \text{ K}^{-1}$ Along c-axis: $1.71 \cdot 10^{-6} \text{ K}^{-1}$
Dielectric constant	17
Thermal conductivity	At 12 K: $360 \text{ W.m}^{-1}.\text{K}^{-1}$ At 300 K: $8.82 \text{ W.m}^{-1}.\text{K}^{-1}$ At 450 K: $7.50 \text{ W.m}^{-1}.\text{K}^{-1}$
Dielectric loss tangent (at 10 GHz)	$8 \cdot 10^{-4}$ at 77 K
OPTICAL PROPERTIES	
Transmission range	240 to 6670 nm

STRONTIUM LANTHANUM GALLATE $\text{SrLaGa}_3\text{O}_7$ SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 18 - 20 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal $a = 0.806 \text{ nm}$ $c = 0.534 \text{ nm}$

CRYSTALLOGRAPHIC PROPERTIES	
Color	Orange
PHYSICAL PROPERTIES	
Density	5.2 g.cm ⁻³
Melting point	1760°C
Dielectric constant	22
Loss tangent (at 1 MHz)	5.7.10 ⁻⁵ at 300 K

STRONTIUM LANTHANUM GALLATE SrLaGaO₄ SUBSTRATE

APPLICATIONS

High quality YBaCuO, BiSrCaCuO, Bi(Pb)CaCuO and TlBaCaCuO thin films have been grown on SrLaGaO₄ substrates by different techniques.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 18 - 20 mm
Standard thickness	0.5 to 1 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal a = 0.3843 nm c = 1.2680 nm
Twin structure	No
Color	Colorless to yellow
PHYSICAL PROPERTIES	
Density	6.389 g.cm ⁻³
Melting point	1520°C
Thermal expansion	Along a-axis: 10.1.10 ⁻⁶ K ⁻¹ Along c-axis: 1890.10 ⁻⁵ K ⁻¹
Dielectric constant	22
Loss tangent (at 10 GHz)	5.7.10 ⁻³ at 77 K

STRONTIUM TITANATE SrTiO_3 SUBSTRATE

SrTiO_3 single crystal provides a good lattice match to most materials with Perovskite structure. It is an excellent substrate for epitaxial growth of HTS and many

oxide thin films. SrTiO_3 single crystal has also been used widely for special optical windows and as high quality sputtering target.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Verneuil
Maximum size	Ø 2"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.3905 nm
Twin structure	Without twins
Color	Colorless to pale yellow
PHYSICAL PROPERTIES	
Density	5.175 g.cm ⁻³
Melting point	2080°C
Hardness	6 Mohs
Thermal expansion	9.10 ⁻⁶ K ⁻¹
Dielectric constant	~ 300
Loss Tangent (at 10 GHz)	2.10 ⁻² at 77 K
CHEMICAL PROPERTIES	
Chemical stability	Insoluble in water

Doped SrTiO_3 is used in the basic research and is applied as conducting material [e.g. back side contacting, application of certain surface sensitive measurements (STM)].

DOPANDS	Nb		La	
CONCENTRATION AT %	AVAILABLE	RESISTIVITY (Ω.cm)	AVAILABLE	RESISTIVITY (Ω.cm)
0.02	X	-	-	-
0.05	X	0.08	X	0.12
0.1	X	0.03	X	-
0.2	X	-	-	-
0.5	X	0.005	X	0.006
1.0	X	0.003	X	-
2.0	X	-	-	-
5.0	-	-	X	0.0007

TITANIUM OXIDE (RUTILE) TiO_2 SUBSTRATE

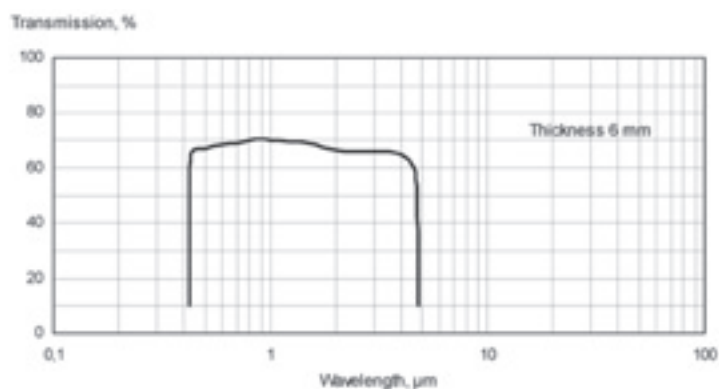
Rutile (TiO_2) single crystal is one of the most suitable materials for spectral prisms and polarizing devices such as optical isolators and beam displacers because it has a

large birefringence with a high refractive index. Compared to YVO_4 , TiO_2 crystal is more stable chemically and physically.

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Floating zone (FZ)
Maximum size	Ø 1"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Tetragonal $a = 0.459 \text{ nm}$ $c = 0.296 \text{ nm}$
Color	Pal
PHYSICAL PROPERTIES	
Density	4.26 g.cm^{-3}
Melting point	1825°C
Hardness	7 Mohs
Thermal expansion	Vertical c-axis: $7.2 \cdot 10^{-6} \text{ K}^{-1}$ Parallel c-axis: $9.19 \cdot 10^{-6} \text{ K}^{-1}$
Specific heat capacity	$710 \text{ J.kg}^{-1}.\text{K}^{-1}$
Thermal conductivity	$12.56 \text{ W.m}^{-1}.\text{K}^{-1}$
Resistivity	$7 \cdot 10^7 \Omega.\text{cm}$
Dielectric constant	Vertical c-axis: 170 Parallel c-axis: 88
OPTICAL PROPERTIES	
Transmission range (thickness 6 mm)	0.43 - 6.0 μm
Refractive index:	0.6 μm
	n_o 2.61
	n_e 2.90

TRANSMISSION SPECTRUM

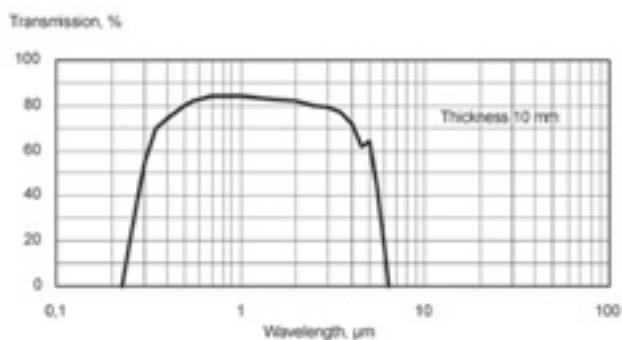


YTTRIUM ALUMINIUM GARNET $\text{Y}_3\text{Al}_5\text{O}_{12}$ (YAG) SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH					
Growth method	Czochralski (CZ)				
Maximum size	Ø 2"				
CRYSTALLOGRAPHIC PROPERTIES					
Crystal structure	Cubic a = 1.2005 nm				
Color	Colorless				
PHYSICAL PROPERTIES					
Density	4.55 g.cm ⁻³				
Melting point	1940°C				
Hardness	8.5 Mohs				
Thermal expansion	6.9.10 ⁻⁶ K ⁻¹				
Transmission range (thickness 1 mm)	0.3 - 0.5 µm				
Solubility in water	Insoluble				
Solubility in acids	Unessential				
Refractive index n	0.5 µm	1.0 µm	2.0 µm	3.0 µm	4.0 µm
	1.845	1.8197	1.8035	1.7855	1.7602

TRANSMISSION SPECTRUM



YTTRIUM ALUMINATE YAlO_3 (YAP) SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Czochralski (CZ)
Maximum size	Ø 1.5"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Orthorhombic a = 0.517 nm b = 0.5307 nm c = 0.7355 nm
Twin structure	No
Color	Colorless
PHYSICAL PROPERTIES	
Density	4.88 g.cm ⁻³
Melting point	1870°C
Thermal expansion	2 - 10.10 ⁻⁶ K ⁻¹
Dielectric constant	16 - 20

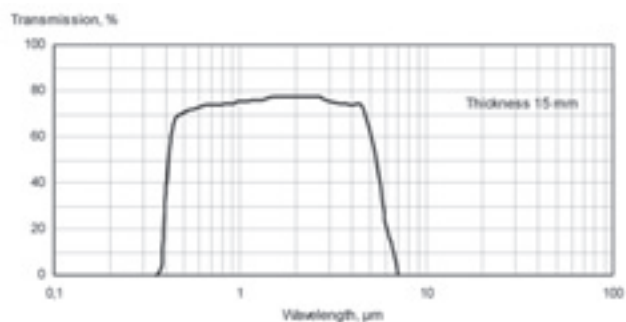
YTTRIA STABILIZED ZIRCONIA (YSZ) SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Skull melting ($\text{ZrO}_2/\text{Y}_2\text{O}_3$ 92-8% wt)
Maximum size	Ø 2"
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic a = 0.5125 nm
Color	Colourless
PHYSICAL PROPERTIES	
Density	5.92 g.cm ⁻³
Melting point	2780°C
Hardness	7.5 - 8 Mohs
Thermal expansion	8.10 ⁻⁶ K ⁻¹
Dielectric constant	27
Thermal conductivity	31.8 W.m ⁻¹ .K ⁻¹
CHEMICAL PROPERTIES	
Solubility in water (g/100 cm ³)	Not declare
Solubility in acids	Not declare
Solubility in organic solvents	Not declare

OPTICAL PROPERTIES	
Refractive index n	4 μm
	2.24

TRANSMISSION SPECTRUM



ZINC OXIDE ZnO SUBSTRATE

STANDARD SPECIFICATIONS

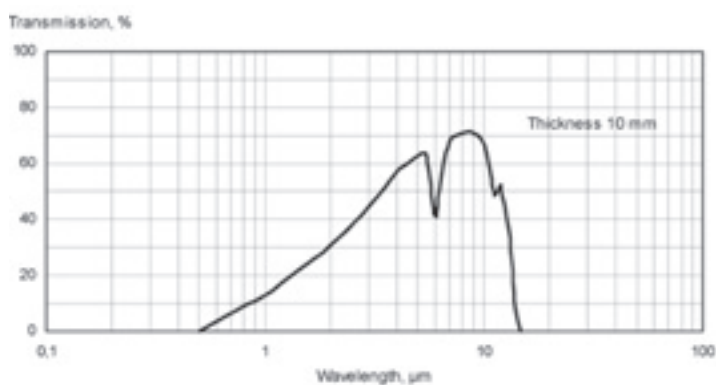
CRYSTAL GROWTH	
Growth method	Hydrothermal, seeded vapor phase growth
Maximum size	\varnothing 35 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Hexagonal $a = 0.3252 \text{ nm}$ $c = 0.5213 \text{ nm}$
PHYSICAL PROPERTIES	
Density	5.7 g.cm^{-3}
Melting point	1975°C
Hardness	4 Mohs
Thermal expansion	$3.16 \cdot 10^{-6} \text{ K}^{-1}$
Resistivity range	$> 10^2 - 10^4 \Omega.\text{cm}$
Band gap at 300 K	3.2 eV
Thermal conductivity	$2.5 \text{ W.m}^{-1}.\text{K}^{-1}$
Conductivity type	N-type
Carrier concentration	$10^{10} \text{ to } 10^{18} \text{ cm}^{-3}$
Dielectric constant	8.5
OPTICAL PROPERTIES	
Refractive index n	$n_o = 2.026$, $n_e = 2.041$

ZINC SULFIDE ZnS SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH						
Growth method	Seeded vapour phase growth					
Maximum size	Ø 40 mm					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Cubic a = 0.5411 nm					
PHYSICAL PROPERTIES						
Density	4.09 g.cm ⁻³					
Melting point	1830°C					
Hardness	3 Mohs					
Thermal expansion	7.9.10 ⁻⁶ K ⁻¹					
Resistivity range	> 10 ² -10 ⁴ Ω.cm					
Band Gap (at 300 K)	3.66 eV					
Thermal conductivity	1.73 W m ⁻¹ .K ⁻¹					
Conductivity type	N-type					
Carrier concentration	10 ⁵ to 10 ¹⁶ cm ⁻³					
Dielectric constant	9.67					
	5.13					
Specific heat capacity	530 J.kg ⁻¹ .K ⁻¹					
CHEMICAL PROPERTIES						
Solubility in water	Insoluble					
Solubility in acids	Unessential					
Solubility in organic solvents	Insoluble					
OPTICAL PROPERTIES						
Absorption coefficient	0.001 cm ⁻¹ at 2.7 μm 0.2 cm ⁻¹ at 10 μm					
Transmission range (thickness 10 mm)	0.4 - 12.5 μm					
Refractive index n	0.5 μm	0.7 μm	1.0 μm	10.0 μm	11.0 μm	12.0 μm
	2.419	2.332	2.292	2.201	2.186	2.161

TRANSMISSION SPECTRUM

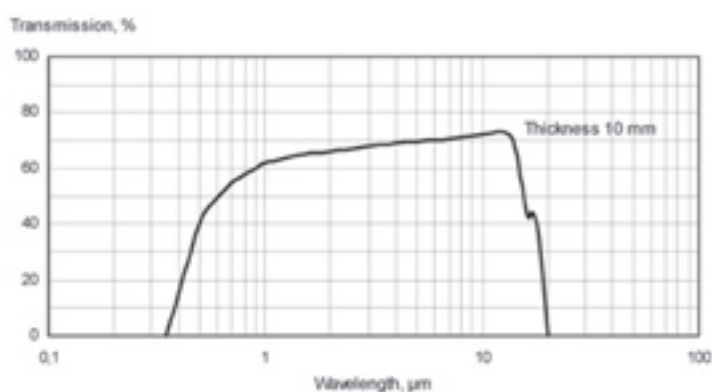


ZINC SELENIDE ZnSe SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH						
Growth method	Seeded vapour phase growth					
Maximum size	Ø 40 mm					
CRYSTALLOGRAPHIC PROPERTIES						
Crystal structure	Cubic a = 0.5668 nm					
Cleavage	<110>					
PHYSICAL PROPERTIES						
Density	5.26 g.cm ⁻³					
Melting point	1520°C					
Hardness	4 Mohs					
Thermal expansion	7.6.10 ⁻⁶ K ⁻¹					
Thermal conductivity	12.97 W.m ⁻¹ .K ⁻¹					
Specific heat capacity	355 J.kg ⁻¹ .K ⁻¹					
Resistivity range	> 10 ⁸ Ω.cm					
Band Gap (at 300 K)	3.66 eV					
Conductivity type	N-type					
Carrier concentration	10 ⁵ to 10 ¹⁷ cm ⁻³					
CHEMICAL PROPERTIES						
Solubility in water	Insoluble					
Solubility in acids	Soluble					
Solubility in organic solvents	Insoluble					
OPTICAL PROPERTIES						
Absorption coefficient	0.005 cm ⁻¹ at 10.6 μm					
Transmission range (thickness 10mm)	0.55 - 18.0 μm					
Refractive index n	1.0 μm	3.0 μm	5.0 μm	10.0 μm	12.0 μm	15.0 μm
	2.4894	2.4376	2.4296	2.4067	2.3936	2.3662

TRANSMISSION SPECTRUM



ZINC TELLURIDE ZnTe SUBSTRATE

STANDARD SPECIFICATIONS

CRYSTAL GROWTH	
Growth method	Seeded vapour phase growth
Maximum size	Ø 40 mm
CRYSTALLOGRAPHIC PROPERTIES	
Crystal structure	Cubic $a = 0.6089 \text{ nm}$
PHYSICAL PROPERTIES	
Density	5.636 g.cm^{-3}
Melting point	1290°C
Hardness	4 Mohs
Thermal expansion	$8.36 \cdot 10^{-6} \text{ K}^{-1}$
Resistivity range	$> 10^5 \Omega.\text{cm}$
Band gap (at 300 K)	2.28 eV
Thermal conductivity	$12.39 \text{ W.m}^{-1}.\text{K}^{-1}$
Conductivity type	P-type
Carrier concentration	$10^{10} \text{ to } 10^{17} \text{ cm}^{-3}$
Dielectric constant	8.1
	7.28
OPTICAL PROPERTIES	
Refractive index n	2.68

Glass & Fused Quartz Substrates

BOROSILICATE GLASS

Borosilicate glass, known under trade names such as Pyrex® and Duran®, is widely used in chemical and engineering applications.

This glass is chemically resistant, has a low thermal expansion coefficient and can be used at relatively high temperatures. Our high quality borosilicate glass substrates are optically polished on both surfaces. The excellent

flatness and a low warp of our borosilicate wafers and the thermal coefficient of expansion close to the one of silicon, facilitate sophisticated applications in the semiconductor industry such as anodic bonding to silicon and various micro optical applications.

On request, our borosilicate glass wafers can be made with a ground SEMI standard flat or a notch.

APPLICATIONS

- Semiconductor applications
- Micro lithography
- Substrates for anodic bonding
- Optical substrates
- Micro system technology
- Micro mechanics
- Microstructure applications

STANDARD SPECIFICATIONS

GENERAL PROPERTIES	
Density	2.23 g.cm ⁻³
MECHANICAL PROPERTIES	
Young's modulus	64 GPa
Hardness (Knoop test)	480

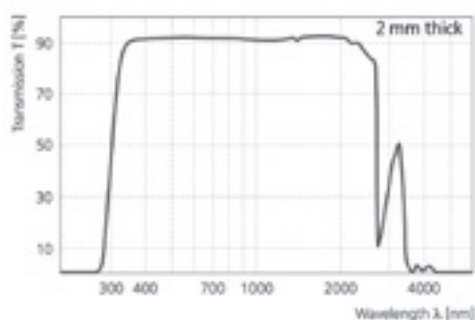
THERMAL PROPERTIES	
Max. use temperature	500°C
Thermal conductivity	1.14 W.m ⁻¹ .K ⁻¹
Coefficient of linear expansion	3.3.10 ⁻⁶ K ⁻¹
ELECTRICAL PROPERTIES	
Volume resistance	10 ¹⁵ Ω.cm
Dielectric constant	4.6 (20°C, 1 MHz)
Dielectric strength	30 kV.mm ⁻¹
OPTICAL PROPERTIES	
Refractive index n	1.474 at 588 nm

AVAILABLE THICKNESS

THICKNESS (mm)	TOLERANCE (mm)
0.7	+/- 0.07
1.1	+/- 0.1
1.75	+/- 0.2
2	+/- 0.2
2.25	+/- 0.2
2.75	+/- 0.2
3.3	+/- 0.2
3.8	+/- 0.2
5	+/- 0.2
6.5	+/- 0.2
7.5	+/- 0.3
9	+/- 0.3
11	+/- 0.3
13	+/- 0.3
15	+/- 0.3
17	+/- 0.5
19	+/- 0.5
21	+/- 0.7
25.4	+/- 1.0

Other thickness are available on request.

TRANSMISSION SPECTRUM



QUARTZ/SILICA SUBSTRATE

Quartz glass is an extremely versatile material used in a range of different applications. It has outstanding thermal properties, excellent optical transmission, with good electrical and corrosion performance.

There are two basic ways of making quartz / silica glass:

- By melting silica grains either by gas or electrical heating (the type of heating affects some optical properties). This material can be transparent or, for some applications, opaque.
- By synthesising the glass from chemicals.

This synthetic material, normally referred to as synthetic fused silica, has better optical properties and is somewhat more expensive than the other type.

ADVANTAGES

- Incredibly thermally shock resistant (can be taken from red heat and plunged into water without cracking)
- Low coefficient of thermal expansion
- Optical transmission properties from ultra violet to infra red
- Good chemical resistance
- Excellent electrical insulator

APPLICATIONS

- Windows
- Lenses
- Mirror substrates
- Crucibles, trays and boats
- UV transmitting optics (synthetic fused silica)
- IR transmitting optics
- Metrology components

DIFFERENCES BETWEEN FUSED SILICA AND QUARTZ WAFER

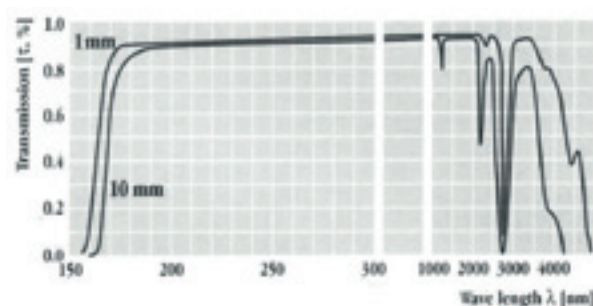
Very often terms such as quartz, silica, fused quartz and fused silica tend to be used interchangeably.

FUSED SILICA WAFER (SYNTHETIC SILICA)	FUSED QUARTZ WAFER (NATURAL SILICA)
<ul style="list-style-type: none"> • High OH content >1200 • Excellent optical properties • Higher transmission in the UV range • Free bubbles, inclusions and contaminants • Very low fluorescence • Impurity 5 ppm 	<ul style="list-style-type: none"> • Low OH content > 150 • Excellent thermal properties • Contain some bubbles, inclusions and contaminants • High fluorescence • Impurity 20 - 40 ppm

STANDARD SPECIFICATIONS

GENERAL PROPERTIES	
Density	2.2 g.cm ⁻³
MECHANICAL PROPERTIES	
Young's modulus	72 Gpa
Design tensile strength	48 Mpa
Design compressive strength	1100 Mpa
THERMAL PROPERTIES	
Max. Use temperature	950 - 1300°C
Thermal conductivity	1.4 W.m ⁻¹ .K ⁻¹
Coefficient of linear expansion	0.55.10 ⁻⁶ K ⁻¹
ELECTRICAL PROPERTIES	
Volume resistance	1016 Ω.cm
Dielectric constant	3.7 (20°C, 1 MHz)
Dielectric strength	40 kV.mm ⁻¹

TRANSMISSION SPECTRUM



OPTICAL TRANSMISSION

WAVELENGTH (nm)	FUSED SILICA (SYNTHETIC SILICA)	FUSED QUARTZ (NATURAL SILICA)
190	86.42	73.84
200	86.88	75.16
210	88.51	79.90
220	89.09	85.69
230	89.58	87.57
240	89.90	87.58
250	90.12	88.64
260	90.46	90.11
280	90.89	90.82
300	91.14	91.15
350	91.49	91.45
400	91.72	91.75
500	92.08	91.99
750	92.26	92.32
1000	92.52	92.48
2000	93.25	93.48
2500	91.58	93.56

Ceramic Substrates

ALUMINA Al_2O_3 SUBSTRATE (MICROPOLISHED)

Pure alumina ceramics due to their high insulation resistance at elevated temperatures, high dielectric strength, low dielectric loss tangent at high frequencies is one of the best dielectric materials available for use in applications requiring electrical insulation.

The mechanical strength of pure alumina ceramics may be extremely high if properly controlled by the size and homogeneity of the constituent crystallites. It is recommended to use ceramics in compression because

compressive strength is nearly 10 times that of the flexural strength. This may be achieved through design or by the establishment of operating conditions.

Thermal and chemical properties of pure alumina ceramics are always of great interest. Thermal conductivity is nearly equivalent to stainless steel. Pure alumina ceramics is inert to oxidation, not corroded by chemical agents and not subjected to radiation damage.

APPLICATIONS

- Mechanical seal faces
- Nozzles for abrasives spraying corrosive reagents
- High pressure liquid media
- Laboratory apparatus components
- Metalized parts of high vacuum and high-voltage feed-through, and many other applications

STANDARD SPECIFICATIONS

Purity	96%
Color	White
Density	3.72 g.cm ⁻³
Thermal expansion	8.10 ⁻⁶ °C ⁻¹
Loss tangent	4.10 ⁻⁴ at 1 MHz

Thermal conductivity	24 W.m ⁻¹ .K ⁻¹
Dielectric constant (at 1 MHz)	9.8
Volume resistivity (Ω.m)	> 10 ¹³ at 20°C > 3.10 ⁷ at 500°C
Flexural strength	350 N.mm ⁻²

Glassy Carbon Substrates

Glassy carbon, also called vitreous carbon, is an advanced material of pure carbon combining glassy and ceramic properties with those of graphite. Unlike graphite, glassy

carbon has a fullerene-related microstructure. This leads to a great variety of unique material properties.

SPECIAL PROPERTIES

- High temperature resistance in inert gas or vacuum up to 3000°C
- High purity
- Extreme corrosion resistance
- Impermeability to gas and liquids, no open porosity
- No wetting by melts
- High hardness and strength
- Low density
- High surface quality, no particle generation
- Low thermal expansion
- Extreme resistance to thermal shock
- Isotropy of physical and chemical properties
- Good electrical conductivity
- Biocompatibility

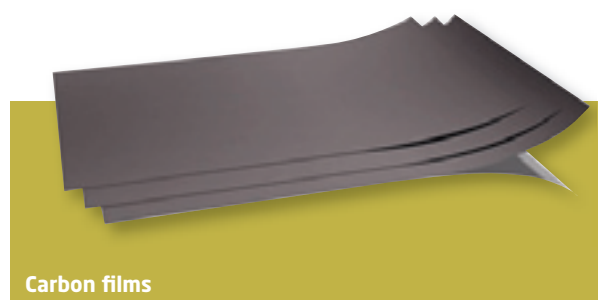
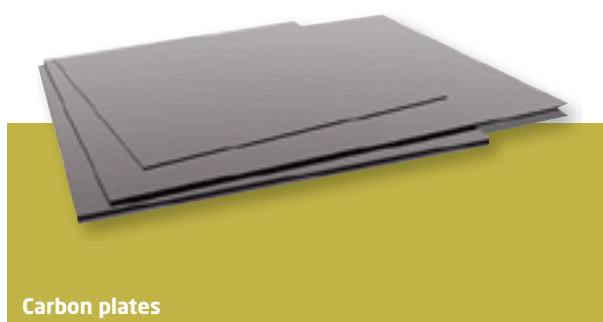
STANDARD SPECIFICATIONS

	PLATES	PLATES / FILMS
Maximum service temperature (vacuum or inert gas)	3000°C	1000°C
Density	1.42 g.cm ⁻³	1.54 g.cm ⁻³
Open porosity	0%	0%
Permeability coefficient	10 ⁻⁹ cm ² .s ⁻¹	10 ⁻¹¹ cm ² .s ⁻¹
Vickers hardness	230 HV1	340 HV1
Flexural strength (4 point)	260 N.mm ⁻²	210 N.mm ⁻²
Young's modulus	35 kN.mm ⁻²	35 kN.mm ⁻²
Compressive strength	480 N.mm ⁻²	580 N.mm ⁻²
Specific electrical resistance (RT)	45 Ω.μm	50 Ω.μm
Thermal conductivity (RT)	6.3 J.K ⁻¹ .m ⁻¹ .s ⁻¹	4.6 J.K ⁻¹ .m ⁻¹ .s ⁻¹
Median linear coefficient of expansion (20-200°C)	2.6.10 ⁻⁶ K ⁻¹	3.5.10 ⁻⁶ K ⁻¹

AVAILABLE DIMENSIONS

	THICKNESS	DIMENSIONS
PLATES	0.3 mm 0.5 mm	25 x 25 mm 50 x 50 mm 100 x 100 mm
	1 to 6 mm	25 x 25 mm 50 x 50 mm 100 x 100 mm 200 x 200 mm
FILMS	60 µm 100 µm 140 µm 180 µm	25 x 25 mm 50 x 50 mm 100 x 100 mm

Other dimensions and custom made parts are available on request.



HOPG & Mica Substrates

HIGHLY ORDERED PYROLYTIC GRAPHITE HOPG

HOPG, is a relatively new form of high purity carbon and provides microscopists with a renewable and smooth surface. Unlike mica, HOPG is completely non-polar, and for samples where elemental analysis will also be done, it provides a background with only carbon in the elemental signature. The extreme smoothness of HOPG gives results in a featureless background, except at atomic levels of resolution.

The structure is strictly columnar, that is, the columns run vertically within the flat slab of the material. The grain boundaries can be seen on the lateral surfaces. The mosaic spread is the angle of deviation of the grain's boundary from this perpendicular axis (of the columnar structure).

USE AT ELEVATED TEMPERATURES

As more and more applications are found for HOPG in research and technology, more and more applications are requiring good high temperature characteristics. We can report the following information which should be useful for those contemplating such usage:

- Air: 500°C (Starts to burn)
- Vacuum at 0.1 Torr: 2500°C
- Inert atmosphere (N₂, Ar, He): 3500°C

DENSITY OF HOPG

The density for all three grades (SPI-1, SPI-2, and SPI-3) is 2.27 g.cm⁻³.

GRADE SPI-1

Comparable to the very best "calibration grade" HOPG and exhibiting a 0.4° +/- 0.1°. This is the most highly ordered, lateral grain size is typically up to about 3 mm but can be as large as 10 mm, and is used primarily for instrument calibration purposes or for research experiments where for some reason, the very ultimate in HOPG order is needed.

GRADE SPI-2

This grade exhibits a mosaic angle as small as 0.8° +/- 0.2°. This grade is slightly less highly ordered than SPI-1 but is acceptable for most users. The lateral grain size can be up to 0.5 mm but can be as large as 1 mm.

GRADE SPI-3

Exhibits a mosaic angle as small as $3.5^\circ \pm 1.5^\circ$. This grade is much less highly ordered and has a grain size not larger than the range of 30-40 nm.

SQUARES & RECTANGLES

DIMENSIONS (mm)	P/N SPI-1 GRADE	P/N SPI-2 GRADE	P/N SPI-3 GRADE
5 x 5 x 1	476HP-AB	479HP-AB	490HP-AB
7 x 7 x 1	498HP-AB	480HP-AB	491HP-AB
10 x 10 x 1	439HP-AB	436HP-AB	429HP-AB
10 x 10 x 2	438HP-AB	446HP-AB	440HP-AB
12 x 12 x 1	426HP-AB	-	-
10 x 10 x 0.2	424HP-AB	-	-
10 x 10 x 3	-	456HP-AB	443HP-AB
20 x 20 x 1	-	466HP-AB	449HP-AB
20 x 20 x 2	-	444HP-AB	448HP-AB
20 x 20 x 3	-	447HP-AB	451HP-AB

DISCS

3 mm diameter to fit into a standard TEM grid holder, 50-75 μm thick, shipped in a BEEM Dial-A-Grid box.

Packaging	P/N
Pack of 20 discs	423HP-CA
Pack of 100 discs	423HP-MB

MICA SHEETS, STRIPS AND DISCS

The only mica offered by Neyco is of the muscovite type and indeed, we offer only the highest qualities of the mineral.

APPLICATIONS

For AFM studies, and for those making either carbon films or doing thin film coating research and wanting a higher quality mica as defined as having fewer “steps” on a freshly cleaved surface, we would recommend grade V-4. This grade is also great for use with AFM where a polar substrate is desired or

where polarity of the substrate just does not matter.

For AFM calibration studies or perhaps the ultimate substrate for carbon film production, we offer the grade V-1. Mica can also be used as a substrate for binding cells to be characterized by TEM.

- Chemical Formula: $\text{K}_2\text{OAl}_2\text{O}_3\text{SiO}_2$
- Appearance: Semi clear to gray translucent sheets, strips, and discs
- Specific Gravity: 2.7 g.cm^{-3}
- Hardness on Mohs scale of hardness: 2 - 2.25

- Grade V-1 Muscovite: Highest possible quality
- Grade V-4 Muscovite: Premium research quality
- Grade V-5 Muscovite: Research quality

SQUARES & RECTANGLES

THICKNESS	LATERAL SIZE (mm)	PACKAGING	GRADE V-1	GRADE V-4	GRADE V-5
0.15 mm	50 x 25	Pkg of 1	01792-AB	-	-
	50 x 25	Pkg of 20	01792-CA	01876-CA	-
	50 x 25	Pkg of 100	01792-MB	01876-MB	-
	25 x 25	Pkg of 1	01872-AB	-	-
	25 x 25	Pkg of 20	01872-CA	-	-
	25 x 25	Pkg of 100	01872-MB	-	-
	15 x 15	Pkg of 20	01868-CA	01869-CA	-
	15 x 15	Pkg of 100	01868-MB	01869-MB	-
	75 x 50	Pkg of 20	-	-	01804-CA
	75 x 25	Pkg of 20	-	-	01805-CA
	75 x 25	Pkg of 100	-	-	01805-MB
	40 x 10	Pkg of 100	-	-	01806-MB
0.26 mm	25 x 25	Pkg of 20	-	01870-CA	-
	25 x 25	Pkg of 100	-	01870-MB	-
	50 x 25	Pkg of 20	-	01791-CA	-
	50 x 25	Pkg of 100	-	01791-MB	-
	75 x 25	Pkg of 20	-	01875-CA	-
	75 x 25	Pkg of 100	-	01875-MB	-
	80 x 40	Pkg of 25	-	01918-CF	-
	40 x 10	Pkg of 10	-	-	01806A-BA
	40 x 10	Pkg of 100	-	-	01806A-MB

DISCS

THICKNESS	DIAMETER (mm)	PACKAGING	GRADE V-1	GRADE V-4	GRADE V-5
0.05 mm	3.05	Pkg of 100	01900-MB	-	-
	3.05	Pkg of 20	01900-CA	-	-
0.15 mm	9.5	Pkg of 100	01873-MB	01874-MB	-
	9.5	Pkg of 20	01873-CA	01874-CA	-
	12	Pkg of 100	01877-MB	01879-MB	-
	15	Pkg of 100	01878-MB	01880-MB	-
	22	Pkg of 100	01920-MB	01921-MB	-
0.26 mm	9.9	Pkg of 20	-	-	01871-CA
	9.9	Pkg of 100	-	-	01871-MB
0.275 to 0.325 mm	12	Pkg of 100	01925-MB	-	-
	25	Pkg of 100	01926-MB	-	-
0.05 mm	3.05	Pkg of 100	-	01923-MB	-
	3.05	Pkg of 20	-	01923-CA	-

Thin Film Deposition

THIN FILM DEPOSITION ON REQUEST

Neyco offers thin films deposition on request on the various substrates such as: Platinum, Gold, ITO, Titanium, Chromium.



See *Silicon Wafers* in this section about *Thermal Oxidation of Si wafers*

ITO-COATINGS ON GLASS SUBSTRATE

Whenever an electrically conductive surface that at the same time offers a high optical transparency is required, ITO-coating glass series are used. ITO-coating glass is achieved by sputter-coating a thin conductive layer of indium-tin-oxide onto high quality glass substrates.

Because of the low electrical sheet resistances we have available, our ITO-coatings have often be used to shield electromagnetic fields while still transmitting most of the visible light.

Our series of conductive transparent oxide coatings feature a SiO_2 passivation layer. This quartz barrier layer is only a few nanometers thick, and is located between the substrate and the ITO-coating. This offers an increased electrical insulation performance and minimizes possible leaching of alkali-oxides from the glass into liquid crystals. The process of coating this SiO_2 passivation layer between the ITO thin film coating and the glass substrate, is advantageous for most electronic applications and is efficiently integrated into the production process.

APPLICATIONS

- Display technology
- Transparent ITO electrode
- ITO coated microscope slide
- Circuit substrate
- Micro structuring application
- Transparent EMF/EMI/EMC/RFI/HF shielding glass
- Flat antennas for mobile communication
- Conducting glass
- De-Icing applications
- Heatable ITO slide & cover slip

SPECIAL PROPERTIES

- Electrically conductive and optically transparent
- High VIS-NIR light transmission
- High quality glass substrate
- SiO₂ barrier layer
- Low roughness
- High sheet resistance homogeneity
- Uniform transmission homogeneity
- Reflecting in the infrared range

REFRACTIVE INDEX

We present the refractive index data for the ITO coating. It is the refractive index value used for calculating our ITO film performances. Remember that the ITO coatings made are sputtered and therefore are denser than coatings made by vacuum evaporation.

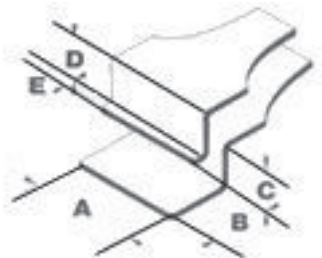
WAVELENGTH (nm)	REFRACTIVE INDEX	EXTINCTION COEFFICIENT
400	2.15	0.025
425	2.1	0.018
450	2	0.01
506	2	0.0087
600	2	0.0065
650	2	0.0044
700	2	0.0042
750	2	0.0042
800	2	0.004
1065	2	0.004

RESISTIVITY RANGE

Resistivity range: 10 - 15, 15 - 30, 30 - 60, 70 - 100 Ω.cm according ITO thickness.

Wafer Tweezers

We offer 18 different tweezers styles, mostly from the SPI-Swiss collection.



STYLE	DIMENSIONS (in mm)				
	A	B	C	D	E
Style #2W	6.5	5	2.5	4	-
Style 2WF	6.5	9	2.5	4	2.5
Style 2WFG	6.5	9	2.5	4	2.5
Style 3W	9.5	10	2.5	4	-
Style 3WF	9.5	10	2.5	4	2.5
Style 3WFG	9.5	10	2.5	4	2.5
Style 4W	12	9	2.5	4	-
Style 4WF	12	9	2.5	4	2.5
Style 4WFG	12	9	2.5	4	2.5

	STYLE	DESCRIPTION	P/N
	Style #2W Length: 120 mm	Antimagnetic Stainless Steel	0S2W0-XD
		PTFE Coated Antimagnetic Stainless Steel	S2W0T-XD
	Style 2WF Length: 119 mm	Antimagnetic Stainless Steel	0S2WF-XD
		PTFE Coated Antimagnetic Stainless Steel	S2WFT-XD
	Style 2WFG Length: 120 mm	Antimagnetic Stainless Steel	S2WFG-XD
		PTFE Coated Antimagnetic Stainless Steel	S2WFGT-XD
	Style 3W Length: 125 mm	Antimagnetic Stainless Steel	0S3W0-XD
		PTFE Coated Antimagnetic Stainless Steel	S3W0T-XD
	Style 3WF Length: 125 mm	Antimagnetic Stainless Steel	0S3WF-XD
		PTFE Coated Antimagnetic Stainless Steel	S3WFT-XD
	Style 3WFG Length: 125 mm	Antimagnetic Stainless Steel	S3WFG-XD
		PTFE Coated Antimagnetic Stainless Steel	S3WFGT-XD
	Style 4W Length: 133 mm	Antimagnetic Stainless Steel	0S04W-XD
		PTFE Coated Antimagnetic Stainless Steel	S04WT-XD
	Style 4WF Length: 133 mm	Antimagnetic Stainless Steel	0S4WF-XD
		PTFE Coated Antimagnetic Stainless Steel	S4WFT-XD
	Style 4WFG Length: 125 mm	Antimagnetic Stainless Steel	S4WFG-XD
		PTFE Coated Antimagnetic Stainless Steel	S4WFGT-XD
	Style 33A Length: 112 mm Width at end: 6.5 mm	Antimagnetic Stainless Steel	0S33A-XD
		PTFE Coated Antimagnetic Stainless Steel	S33AT-XD
	Style 34A Length: 127 mm Width at end: 6.2 mm	Antimagnetic Stainless Steel	0S34A-XD
		PTFE Coated Antimagnetic Stainless Steel	S34AT-XD

	STYLE	DESCRIPTION	P/N
	Style 35A Length: 121 mm Width at end: 6.5 mm	Antimagnetic Stainless Steel	0S35A-XD
		PTFE Coated Antimagnetic Stainless Steel	S35AT-XD
	Style 36A Length: 124 mm Width at end: 6.2 mm	Antimagnetic Stainless Steel	0S36A-XD
		PTFE Coated Antimagnetic Stainless Steel	S36AT-XD
	Style 37S Length: 124 mm Width at end: 6.5 mm	Antimagnetic Stainless Steel	0S37S-XD
		PTFE Coated Antimagnetic Stainless Steel	S37ST-XD
	Style 84A Length (Total): 121 mm Width of pick up: 2 mm Length of top pick up: Top: 5 mm Bottom: 6 mm	Antimagnetic Stainless Steel	0S84A-XD
		PTFE Coated Antimagnetic Stainless Steel	S84AT-XD
	Style 85C Length: 121 mm Width at end: 7.0 mm	Antimagnetic Stainless Steel	0S85C-XD
		PTFE Coated Antimagnetic Stainless Steel	S85CT-XD
	Style 86B Length: 121 mm Width at end: 2.7 mm	Antimagnetic Stainless Steel	0S86B-XD

 See Section L - Sample Preparation in this catalogue for other tweezers.